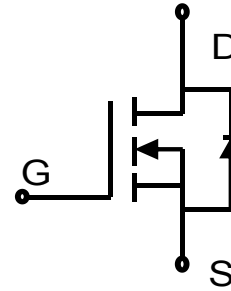




Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.



N-Channel MOSFET

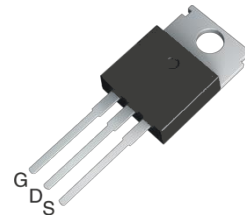
Features

- ◆ 40V, 110A, $R_{DS(ON).max}=5.0m\Omega@V_{GS}=10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

Pin Configuration



TO-220

Product Summary

V_{DSS}	40V
$R_{DS(on).max}@V_{GS}=10V$	5.0mΩ
I_D	110A

Absolute Maximum Ratings $T_c = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	40	V
Continuous drain current ($T_c = 25^\circ C$)	I_D	110	A
Continuous drain current ($T_c = 100^\circ C$)		71	A
Pulsed drain current ¹⁾	I_{DM}	440	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	156	mJ
Power Dissipation ($T_c = 25^\circ C$)	P_D	106	W
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ C$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.17	$^\circ C/W$

Package Marking and Ordering Information

Device	Device Package	Marking
WLP045R04	TO-220	WLP045R04



Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =250μA	40	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0	---	2.0	V
Drain-source leakage current	I _{DSS}	V _{DS} =40 V, V _{GS} =0 V, T _J = 25°C	---	---	1	μA
		V _{DS} =32 V, V _{GS} =0 V, T _J = 125°C	---	---	30	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =20 V, V _{DS} =0 V	---	---	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-20 V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =10 V, I _D =40 A	---	3.8	5	mΩ
		V _{GS} =4.5 V, I _D =30 A	---	4.7	6.2	mΩ
Forward transconductance	g _{fs}	V _{DS} =5 V, I _D =30 A	---	79	---	S
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, F = 1MHz	---	4023.6	---	pF
Output capacitance	C _{oss}		---	410.4	---	
Reverse transfer capacitance	C _{rss}		---	338.5	---	
Turn-on delay time	t _{d(on)}	V _{DD} = 30V, V _{GS} =15V, I _D =30 A	---	231.6	---	ns
Rise time	t _r		---	213.6	---	
Turn-off delay time	t _{d(off)}		---	219.2	---	
Fall time	t _f		---	74	---	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	2.4	---	Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =30 V, I _D =30A, V _{GS} =10V	---	11	---	nC
Gate to drain charge	Q _{gd}		---	16.7	---	
Gate charge total	Q _g		---	66.7	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _S		---	---	110	A
Pulsed Source Current ³⁾	I _{SM}		---	---	440	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =40A, T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _S =20A, di/dt=100A/us, T _J =25°C	---	41.4	---	ns
Reverse Recovery Charge	Q _{rr}		---	29	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: V_{DD}=20V, V_{GS}=10V, L=0.5mH, I_{AS}=25A, R_G=25Ω, Starting T_J=25°C.

3: Pulse Test: Pulse Width ≤300μs, Duty Cycle≤2%.



Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

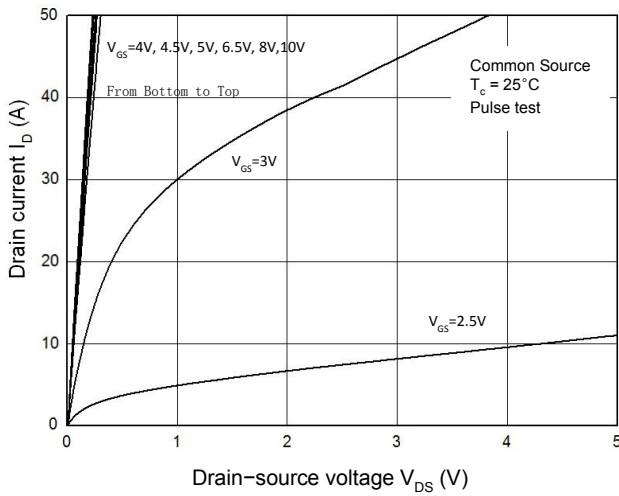


Figure 2. Transfer Characteristics

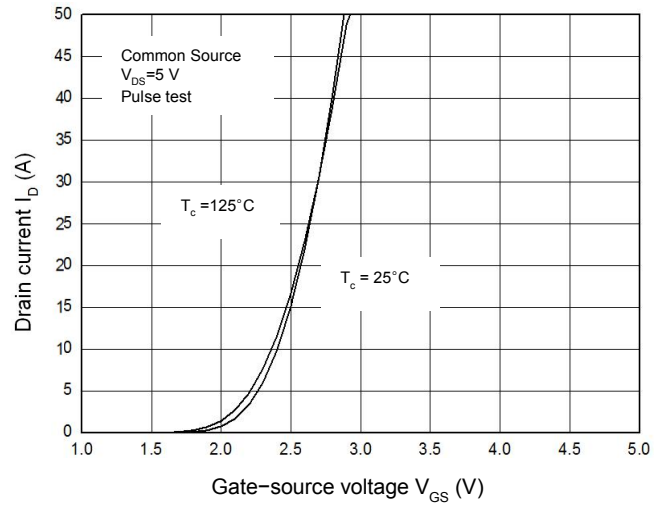


Figure 3. Capacitance Characteristics

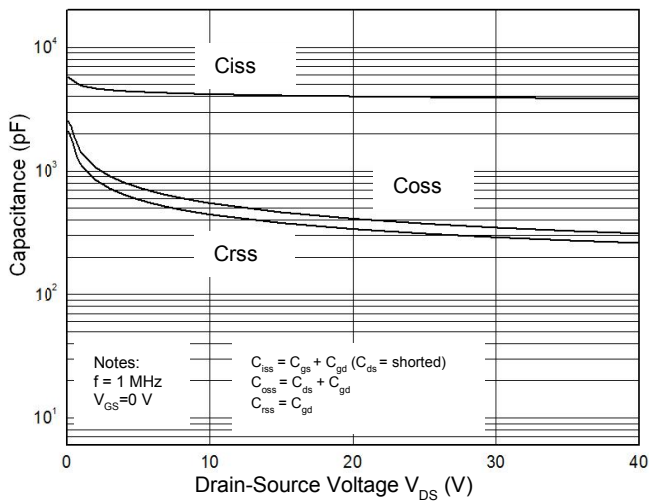


Figure 4. Gate Charge Waveform

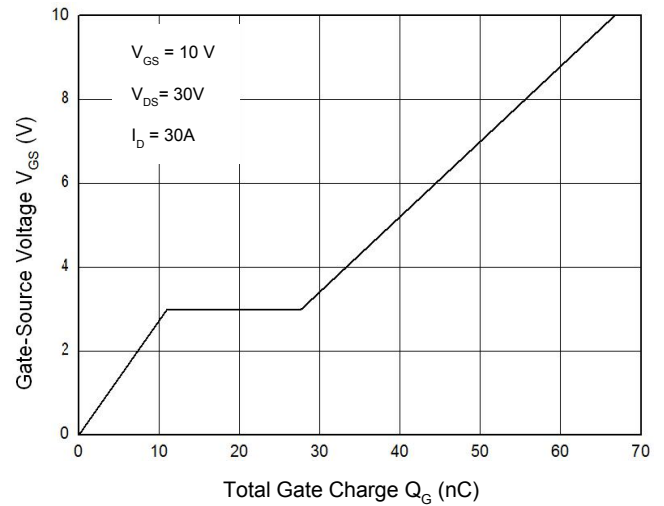


Figure 5. Body-Diode Characteristics

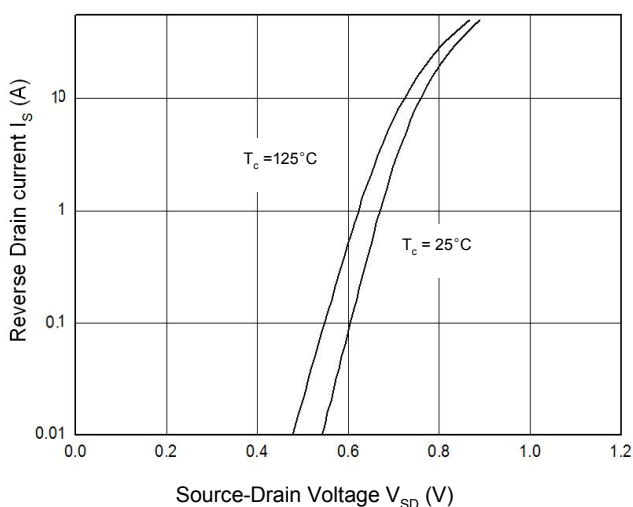


Figure 6. Rds(on)-Drain Current

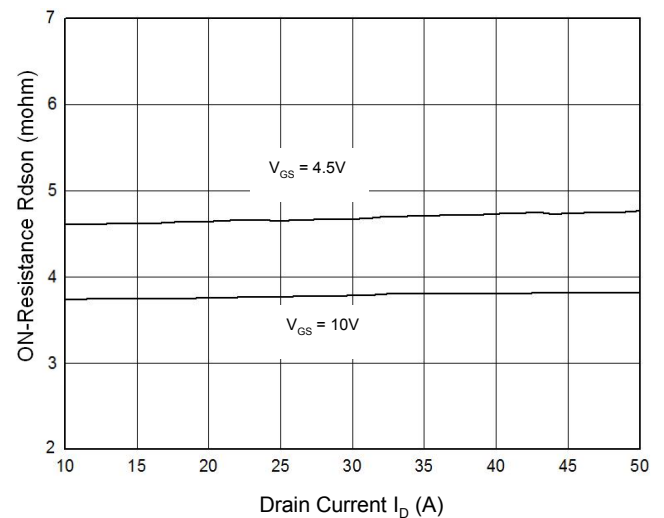




Figure 7. Rdson-Junction Temperature(°C)

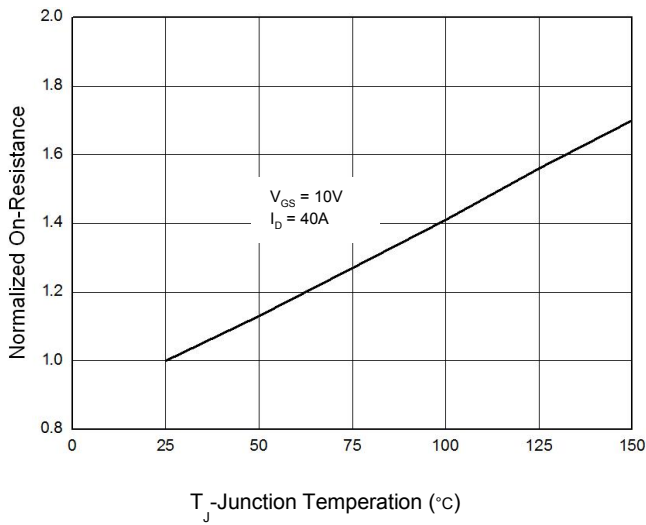


Figure 8. Maximum Safe Operating Area

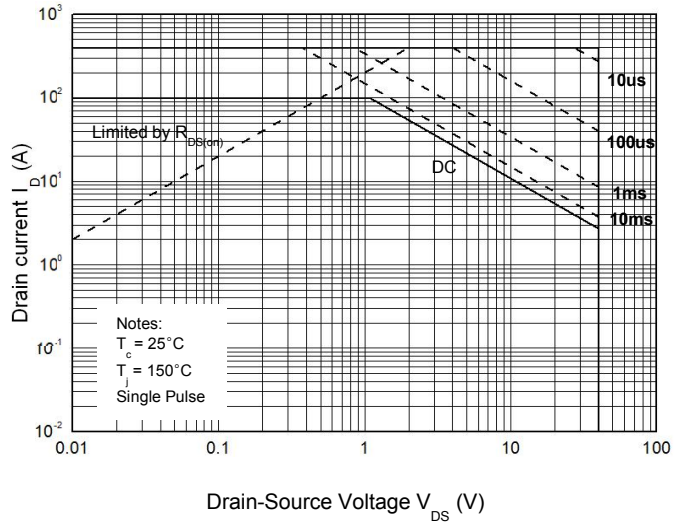
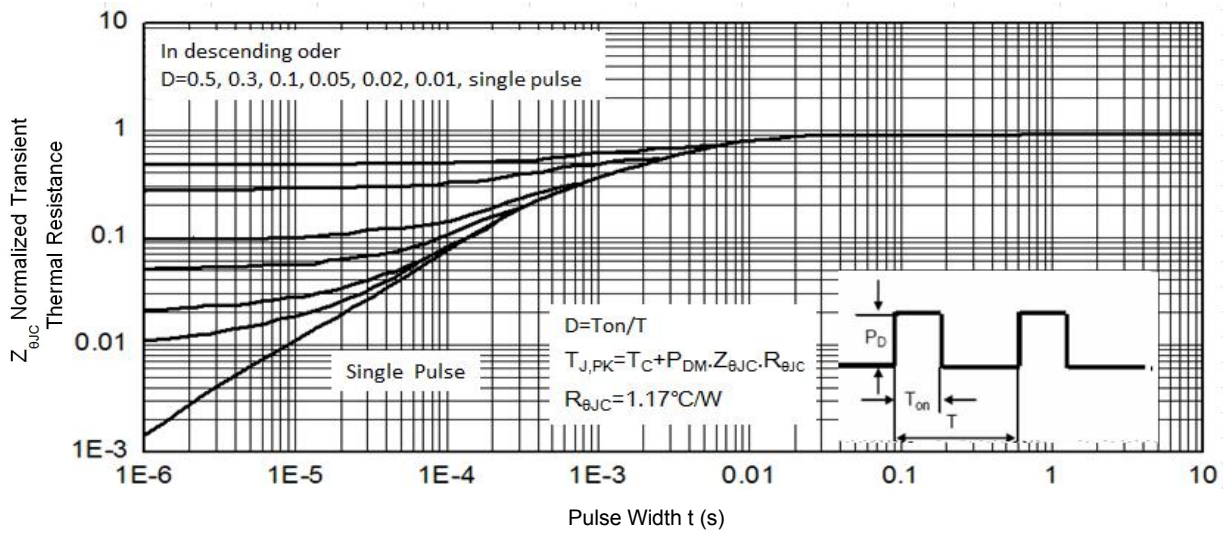


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJC)





Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

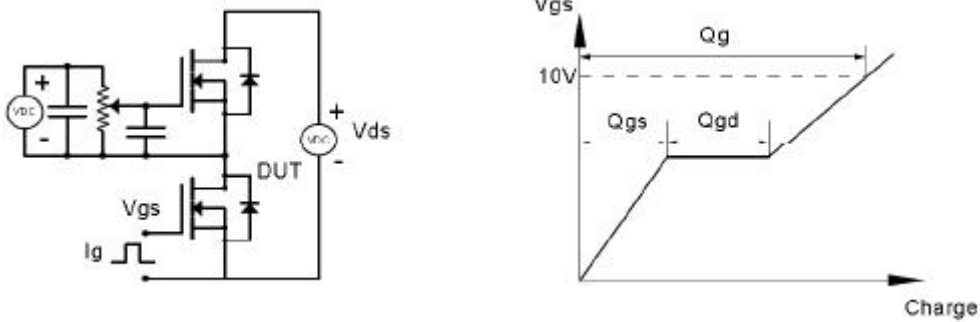


Figure 9. Resistive Switching Test Circuit & Waveforms

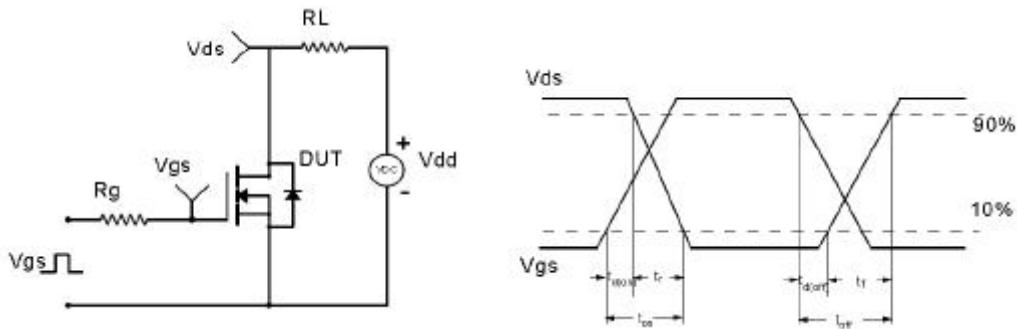


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

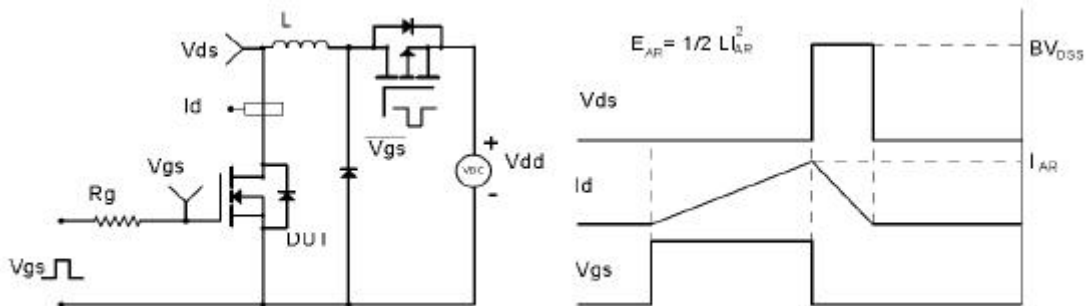
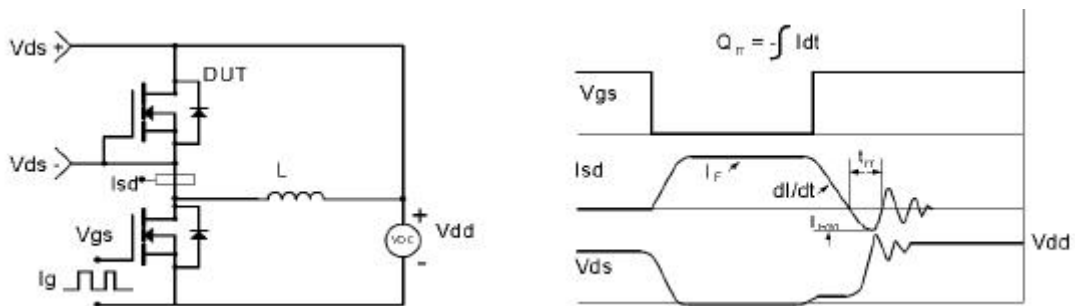
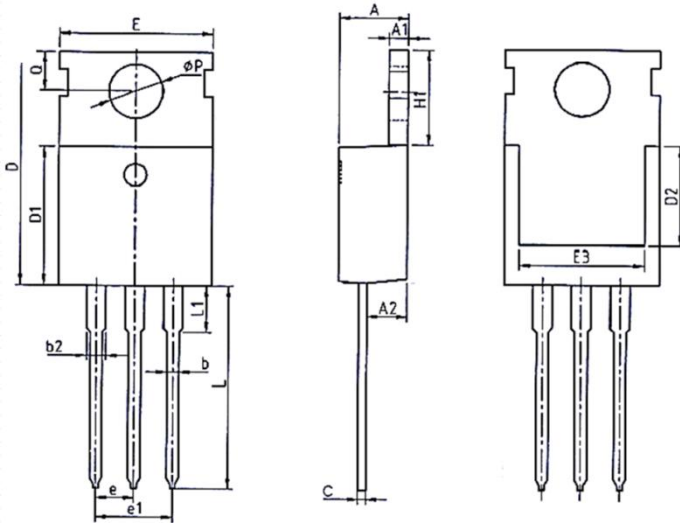


Figure 11. Diode Recovery Circuit & Waveform



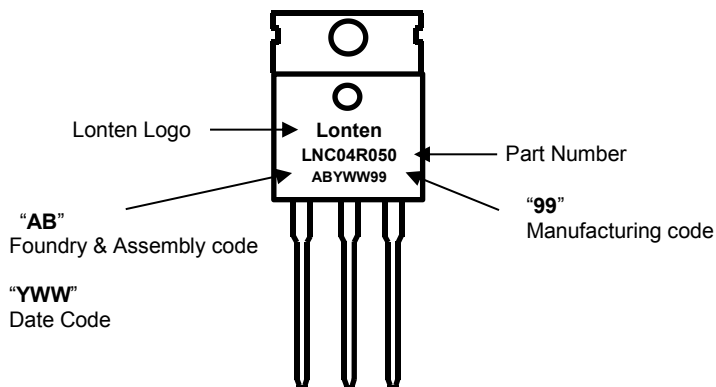


TO-220 PACKAGE INFORMATION



COMMON DIMENSIONS						
SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.37	4.57	4.70	0.172	0.180	0.185
A1	1.25	1.30	1.40	0.049	0.051	0.055
A2	2.20	2.40	2.60	0.087	0.094	0.102
b	0.70	0.80	0.95	0.028	0.031	0.037
b2	1.17	1.27	1.47	0.046	0.050	0.058
c	0.45	0.50	0.60	0.018	0.020	0.024
D	15.10	15.60	16.10	0.594	0.614	0.634
D1	8.80	9.10	9.40	0.346	0.358	0.370
D2	5.50	-	-	0.217	-	-
E	9.70	10.00	10.30	0.382	0.394	0.406
E3	7.00	-	-	0.276	-	-
e	2.54BCS			0.1BSC		
e1	5.08BCS			0.2REF		
H1	6.25	6.50	6.85	0.246	0.256	0.270
L	12.75	13.50	13.80	0.502	0.531	0.543
L1	-	3.10	3.40	-	0.122	0.134
ØP	3.40	3.60	3.80	0.134	0.142	0.150
Q	2.60	2.80	3.00	0.102	0.110	0.118

TO-220 Part Marking Information





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